

N-Channel Enhancement Mode Field Effect Transistor

RC70N06AGD5

Product Summary

- V_{DS} 60V
- I_D 70A
- $R_{DS(ON)}$ (at $V_{GS}=10V$) <7.5 mohm
- $R_{DS(ON)}$ (at $V_{GS}=4.5V$) <9.5 mohm
- 100% UIS Tested
- 100% ∇V_{DS} Tested

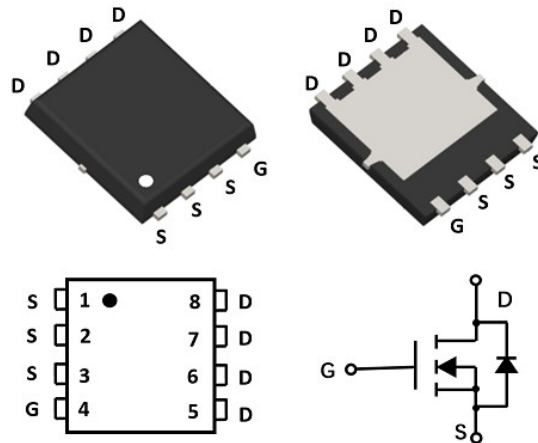
General Description

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$

Applications

- DC-DC Converters
- Power management functions
- Industrial and Motor Drive application

PDFN5060-8L



■ Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		V_{DS}	60	V
Gate-source Voltage		V_{GS}	± 20	V
Drain Current (Silicon limited)	$T_C=25^\circ\text{C}$	I_D	70	A
	$T_C=100^\circ\text{C}$		44	
Pulsed Drain Current ^A		I_{DM}	210	A
Avalanche energy ^B		E_{AS}	162	mJ
Total Power Dissipation ^C	$T_C=25^\circ\text{C}$	P_D	70	W
	$T_C=100^\circ\text{C}$		28	
Junction and Storage Temperature Range		T_J, T_{STG}	-55~+150	$^\circ\text{C}$

■ Thermal resistance

Parameter		Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient ^D	$t \leq 10S$	$R_{\theta JA}$	14	17	$^\circ\text{C/W}$
Thermal Resistance Junction-to-Ambient ^D	Steady-State		40	55	
Thermal Resistance Junction-to-Case	Steady-State	$R_{\theta JC}$	1.3	1.8	

■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
RC70N06AGD5	F1		5000	10000	100000	13" reel

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■ Electrical Characteristics (T_J=25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D =250μA	60			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V, V _{GS} =0V	T _J =25°C		1	μA
			T _J =55°C		5	
Gate-Body Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D =250μA	1.2	1.7	2.5	V
Static Drain-Source On Resistance	R _{DS(on)}	V _{GS} = 10V, I _D =20A		5.3	7.5	mΩ
		V _{GS} = 4.5V, I _D =10A		6.9	9.5	
Diode Forward Voltage	V _{SD}	I _S =20A, V _{GS} =0V		0.85	1.3	V
Maximum Body-Diode Continuous Current	I _S				70	A
Dynamic Parameters						
Input Capacitance	C _{iss}	V _{DS} =35V, V _{GS} =0V, f=1MHZ		2000		pF
Output Capacitance	C _{oss}			390		
Reverse Transfer Capacitance	C _{rss}			13		
Gate Resistance	R _g	f=1MHZ, Open drain		1.6		Ω
Switching Parameters						
Total Gate Charge	Q _g (10V)	V _{DS} =30V, I _D =20A		34		nC
Total Gate Charge	Q _g (4.5V)			15.8		
Gate-Source Charge	Q _{gs}			7.8		
Gate-Drain Charge	Q _{gd}			5.2		
Reverse Recovery Charge	Q _{rr}	I _F =20A, di/dt=200A/us		36		ns
Reverse Recovery Time	t _{rr}			27		
Turn-on Delay Time	t _{D(on)}	V _{GS} =10V, V _{DD} =30V, I _D =12A R _{GEN} =3Ω		10		
Turn-on Rise Time	t _r			36		
Turn-off Delay Time	t _{D(off)}			30		
Turn-off fall Time	t _f			57		

A. Repetitive rating; pulse width limited by max. junction temperature.

B. V_{DD}=50V, R_G=25Ω, L=1mH, I_{AS}=18A,.

C. Pd is based on max. junction temperature, using junction-case thermal resistance.

D. The value of R_{θJA} is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C. The Power dissipation P_{DSM} is based on R_{θJA} ≤ 10s and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.

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Typical Performance Characteristics

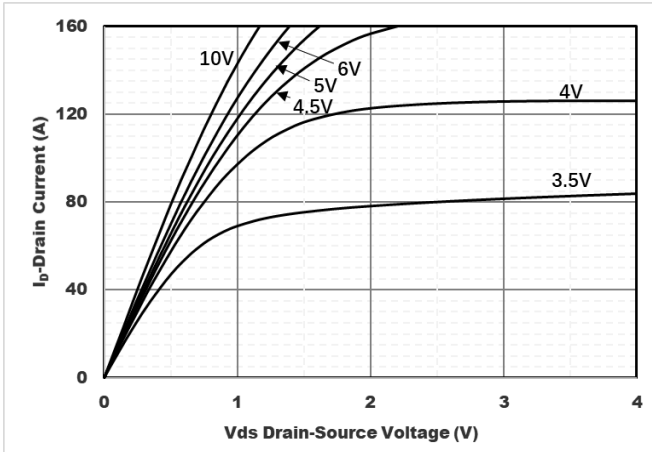


Figure1. Output Characteristics

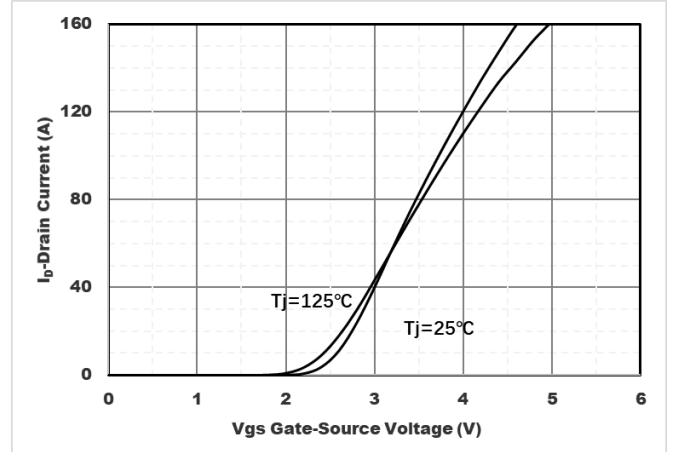


Figure2. Transfer Characteristics

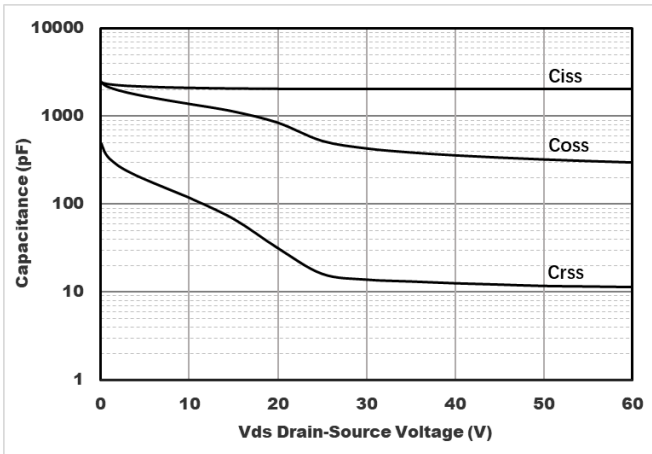


Figure3. Capacitance Characteristics

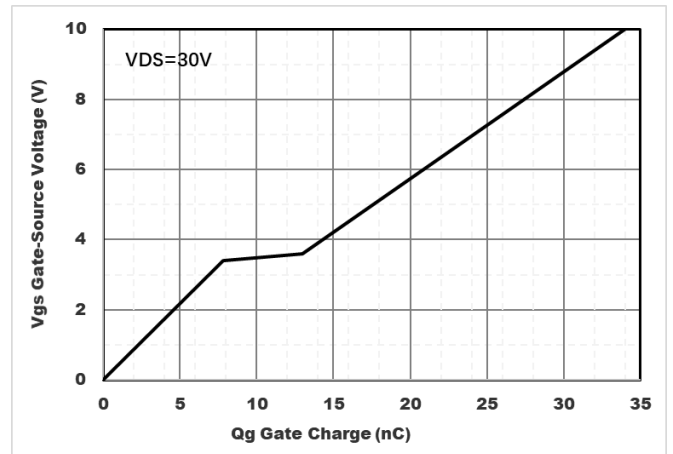


Figure4. Gate Charge

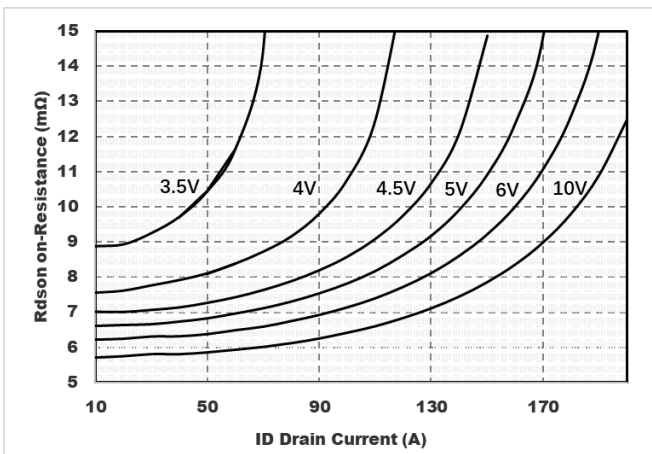


Figure5. Drain-Source on Resistance

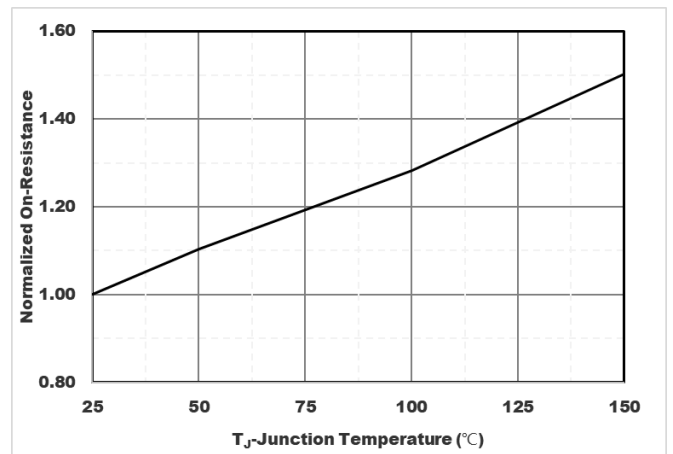


Figure6. Normalized On-Resistance

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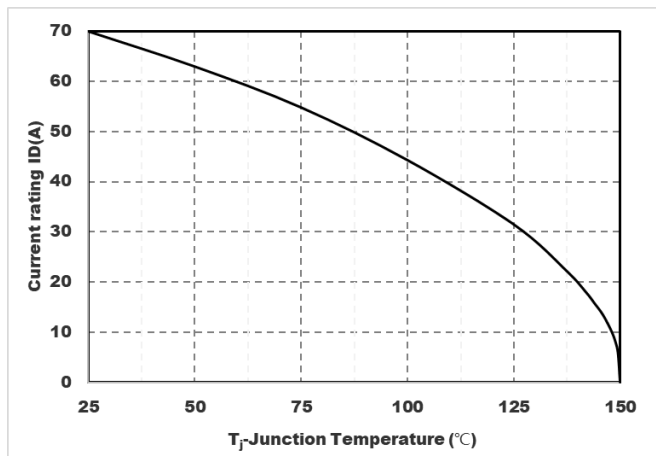


Figure7. Drain current

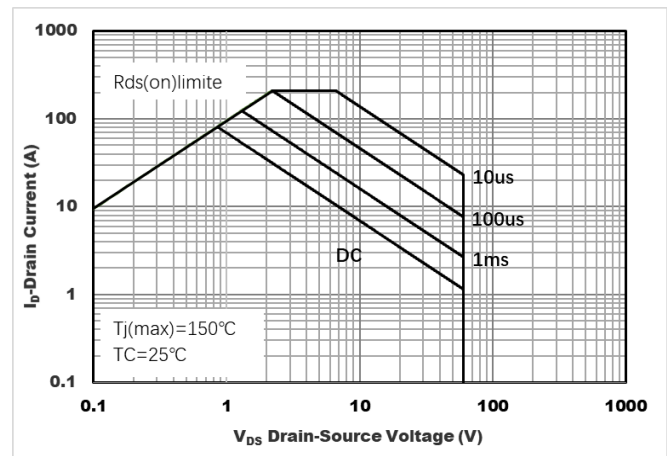


Figure8. Safe Operation Area

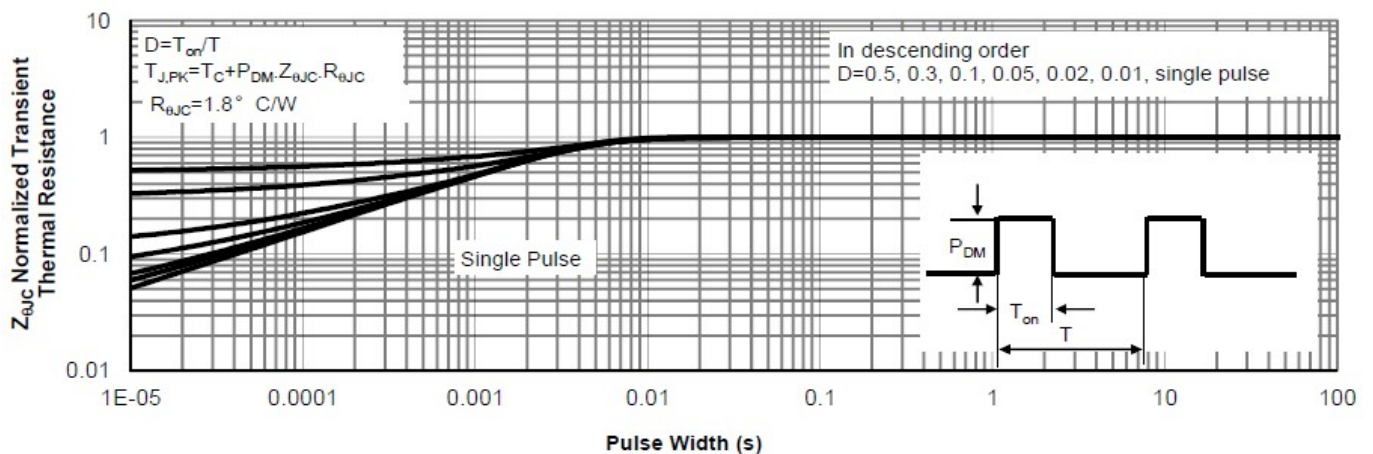
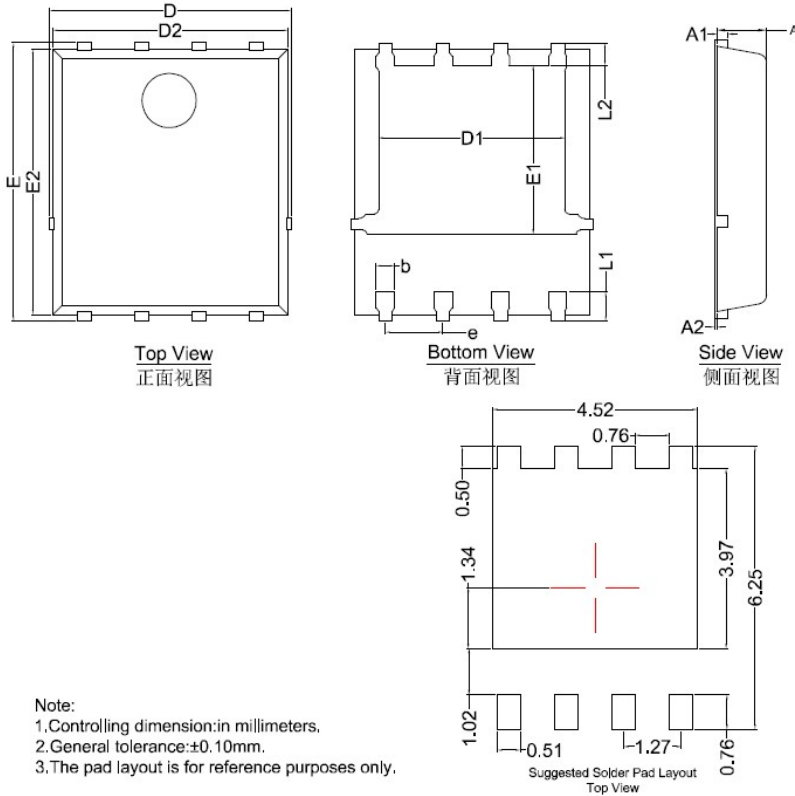


Figure8. Normalized Maximum Transient Thermal Impedance

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■ PDFN5060-8L Package information



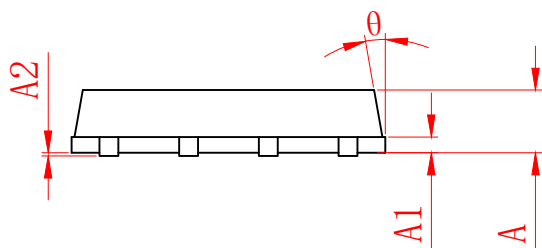
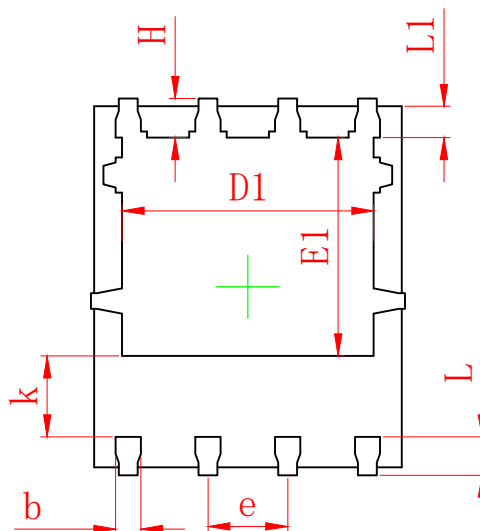
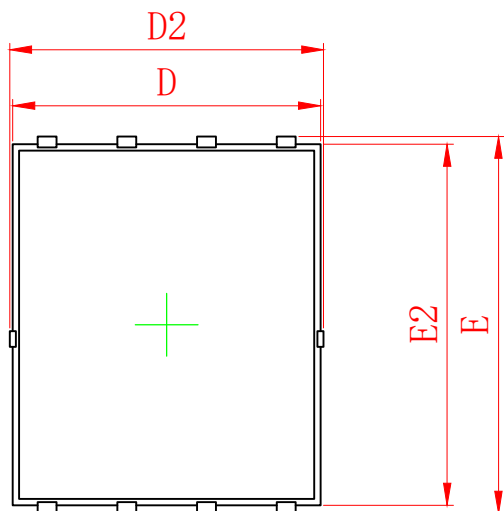
Note:
 1. Controlling dimension: in millimeters.
 2. General tolerance: $\pm 0.10\text{mm}$.
 3. The pad layout is for reference purposes only.

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
D	5.15	5.35	5.55
E	5.95	6.15	6.35
A	1.00	1.10	1.20
A1	0.254 BSC		
A2			0.10
D1	3.92	4.12	4.32
E1	3.52	3.72	3.92
D2	5.00	5.20	5.40
E2	5.66	5.86	6.06
L1	0.56	0.66	0.76
L2	0.50 BSC		
b	0.31	0.41	0.51
e	1.27 BSC		

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■ DFN5x6-8 Package information



SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	0.900	1.000	1.100
A1	0.254REF.		
A2	0~0.05		
D	4.824	4.900	4.976
D1	3.910	4.010	4.110
D2	4.924	5.000	5.076
E	5.924	6.000	6.076
E1	3.375	3.475	3.575
E2	5.674	5.750	5.826
b	0.350	0.400	0.450
e	1.270TYP.		
L	0.534	0.610	0.686
L1	0.424	0.500	0.576
k	1.190	1.290	1.390
H	0.549	0.625	0.701
θ	8°	10°	12°